SN5409, SN54LS09, SN54S09, SN7409, SN74LS09, SN74S09
QUADRUPLE 2-INPUT POSITIVE-AND GATES WITH OPEN-COLLECTOR OUTPUTS

DECEMBER 1983—REVISED MARCH 1988

- **Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs**
- **Dependable Texas Instruments Quality and Reliability**

description

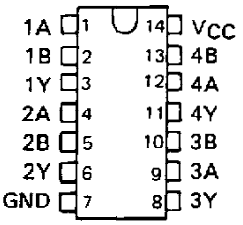
These devices contain four independent 2-input AND gates. The open-collector outputs require pull-up resistors to perform correctly. They may be connected to other open-collector outputs to implement active-low wired-OR or active-high wired-AND functions. Open-collector devices are often used to generate higher V_{OH} levels.

The SN5409, SN54LS09, and SN54S09 are characterized for operation over the full military temperature range of −55°C to 125°C. The SN7409, SN74LS09, and SN74S09 are characterized for operation from 0°C to 70°C.

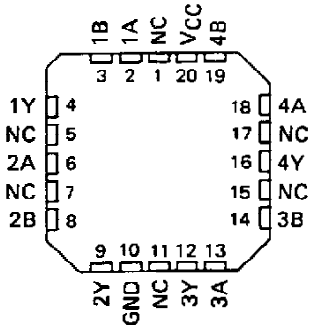
FUNCTION TABLE (each gate)

INPUTS		OUTPUT
A	B	Y
H	H	H
L	X	L
X	L	L

SN5409, SN54LS09, SN54S09 . . . J OR W PACKAGE
SN7409 . . . N PACKAGE
SN74LS09, SN74S09 . . . D OR N PACKAGE
(TOP VIEW)

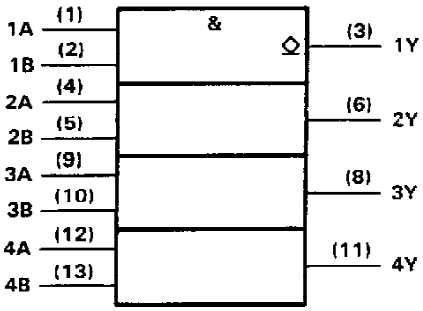


SN54LS09, SN54S09 . . . FK PACKAGE
(TOP VIEW)



NC—No internal connection

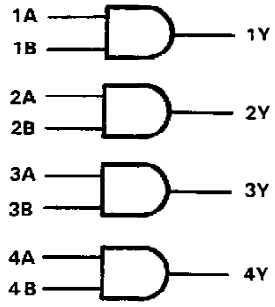
logic symbol



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

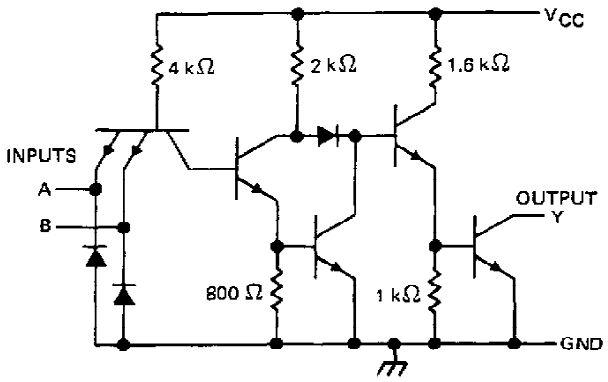
logic diagram (positive logic)



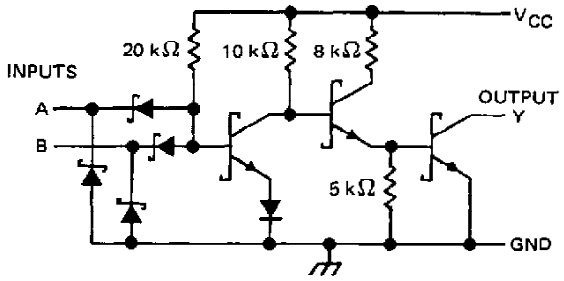
$Y = A \cdot B$ or $Y = \overline{\overline{A} + \overline{B}}$

schematics (each gate)

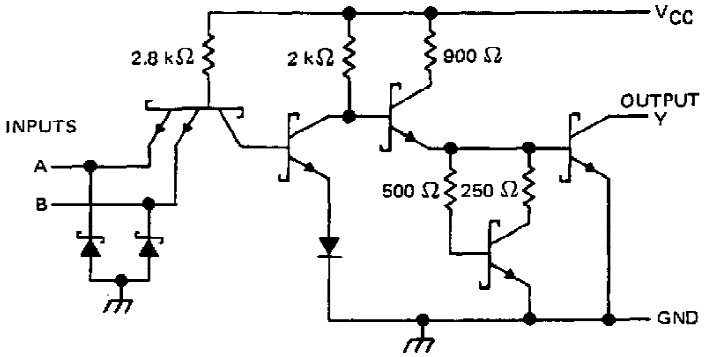
'09



'LS09



'S09



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)		7 V
Input voltage: '09, 'S09		5.5 V
	'LS09	7 V
Off-state output voltage		7 V
Operating free-air temperature range:	SN54'	−55°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range		−65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN5409			SN7409			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_{OH}	High-level output voltage			5.5			5.5	V
I_{OL}	Low-level output current			16			16	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	MIN	TYP‡	MAX	UNIT
V_{IK}	V_{CC} = MIN, I_I = −12 mA			−1.5	V
I_{OH}	V_{CC} = MIN, V_{IH} = 2 V, V_{OH} = 5.5 V			0.25	mA
V_{OL}	V_{CC} = MIN, V_{IL} = 0.8 V I_{OL} = 16 mA		0.2	0.4	V
I_I	V_{CC} = MAX, V_I = 5.5 V			1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.4 V			40	μA
I_{IL}	V_{CC} = MAX, V_I = 0.4 V			−1.6	mA
I_{CCH}	V_{CC} = MAX, V_I = 4.5 V		11	21	mA
I_{CCL}	V_{CC} = MAX, V_I = 0 V		20	33	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A or B	Y	R_L = 400 Ω, C_L = 15 pF		21	32	ns
t_{PHL}					16	24	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

	SN54LS09			SN74LS09			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.7			0.8	V
V_{OH} High-level output voltage			5.5			5.5	V
I_{OL} Low-level output current			4			8	mA
T_A Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS09			SN74LS09			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN, I_I = −18 mA			−1.5			−1.5	V
I_{OH}	V_{CC} = MIN, V_{IH} = 2 V, V_{OH} = 5.5 V			0.1			0.1	mA
V_{OL}	V_{CC} = MIN, V_{IL} = MAX, I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
	V_{CC} = MIN, V_{IL} = MAX, I_{OL} = 8 mA					0.35	0.5	
I_I	V_{CC} = MAX, V_I = 7 V			0.1			0.1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.7 V			20			20	μA
I_{IL}	V_{CC} = MAX, V_I = 0.4 V			−0.4			−0.4	mA
I_{CCH}	V_{CC} = MAX, V_I = 4.5 V		2.4	4.8		2.4	4.8	mA
I_{CCL}	V_{CC} = MAX, V_I = 0 V		4.4	8.8		4.4	8.8	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A or B	Y	R_L = 2 kΩ, C_L = 15 pF		20	35	ns
t_{PHL}					17	35	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

	SN54S09			SN74S09			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.8			0.8	V
V_{OH} High-level output voltage			5.5			5.5	V
I_{OL} Low-level output current			20			20	mA
T_A Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	MIN	TYP‡	MAX	UNIT
V_{IK}	V_{CC} = MIN, I_I = −18 mA			−1.2	V
I_{OH}	V_{CC} = MIN, V_{IH} = 2 V, V_{OH} = 5.5 V			0.25	mA
V_{OL}	V_{CC} = MIN, V_{IL} = 0.8 V, I_{OL} = 20 mA			0.5	V
I_I	V_{CC} = MAX, V_I = 5.5 V			1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.7 V			50	μA
I_{IL}	V_{CC} = MAX, V_I = 0.5 V			−2	mA
I_{CCH}	V_{CC} = MAX, V_I = 4.5 V		18	32	mA
I_{CCL}	V_{CC} = MAX, V_I = 0 V		32	57	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A or B	Y	R_L = 280 Ω, C_L = 15 pF		6.5	10	ns
t_{PHL}					6.5	10	ns
t_{PLH}			R_L = 280 Ω, C_L = 50 pF		9		ns
t_{PHL}					9		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
80019012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	80019012A SNJ54LS 09FK	Samples
8001901CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001901CA SNJ54LS09J	Samples
8001901CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001901CA SNJ54LS09J	Samples
8001901DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001901DA SNJ54LS09W	Samples
8001901DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001901DA SNJ54LS09W	Samples
SN54LS09J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS09J	Samples
SN54LS09J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS09J	Samples
SN54S09J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S09J	Samples
SN54S09J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S09J	Samples
SN7409N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7409N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS09D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS09	Samples
SN74LS09D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS09	Samples
SN74LS09DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS09	Samples
SN74LS09DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS09	Samples
SN74LS09DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS09	Samples
SN74LS09DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS09	Samples
SN74LS09DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS09	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS09DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS09	Samples
SN74LS09DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS09	Samples
SN74LS09DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS09	Samples
SN74LS09J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS09J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS09N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS09N	Samples
SN74LS09N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS09N	Samples
SN74LS09N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS09N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS09NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS09N	Samples
SN74LS09NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS09N	Samples
SN74LS09NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS09	Samples
SN74LS09NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS09	Samples
SN74S09N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S09N	Samples
SN74S09N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S09N	Samples
SN74S09NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S09N	Samples
SN74S09NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S09N	Samples
SN74S09NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74S09	Samples
SN74S09NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74S09	Samples
SNJ54LS09FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	80019012A SNJ54LS	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
										09FK	
SNJ54LS09FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	80019012A SNJ54LS 09FK	Samples
SNJ54LS09J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001901CA SNJ54LS09J	Samples
SNJ54LS09J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001901CA SNJ54LS09J	Samples
SNJ54LS09W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001901DA SNJ54LS09W	Samples
SNJ54LS09W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	8001901DA SNJ54LS09W	Samples
SNJ54S09FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 09FK	Samples
SNJ54S09FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 09FK	Samples
SNJ54S09J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S09J	Samples
SNJ54S09J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S09J	Samples
SNJ54S09W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S09W	Samples
SNJ54S09W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S09W	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF SN54LS09, SN54S09, SN74LS09, SN74S09 :

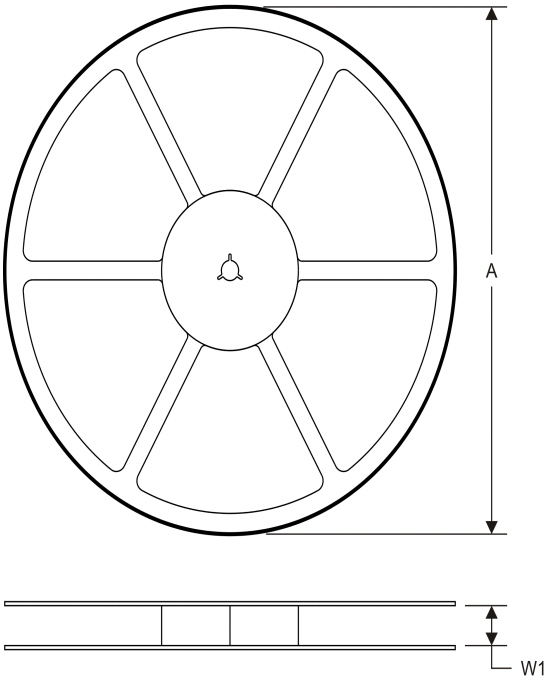
- Catalog: SN74LS09, SN74S09
- Military: SN54LS09, SN54S09

NOTE: Qualified Version Definitions:

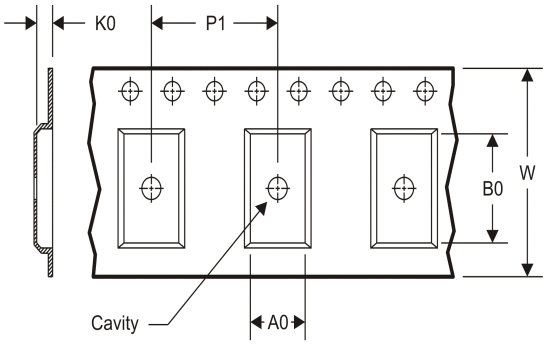
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



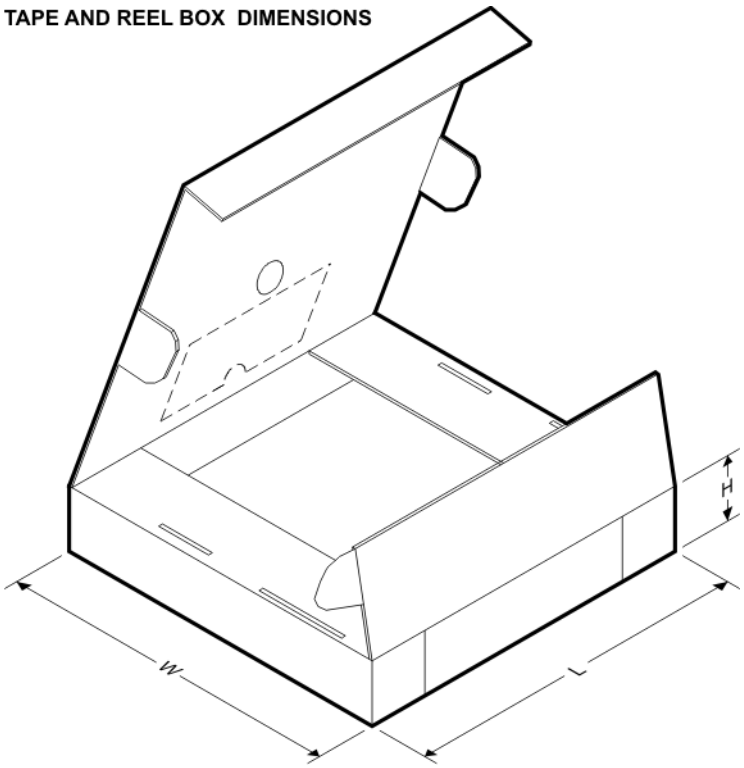
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS09DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS09NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74S09NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



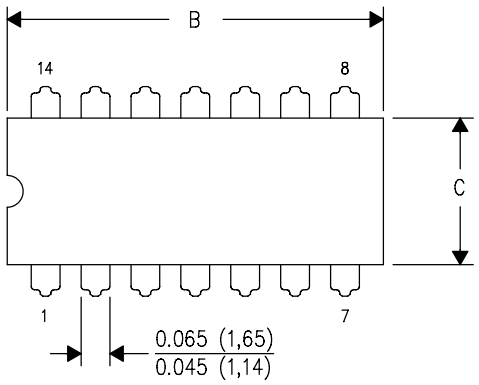
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS09DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LS09NSR	SO	NS	14	2000	367.0	367.0	38.0
SN74S09NSR	SO	NS	14	2000	367.0	367.0	38.0

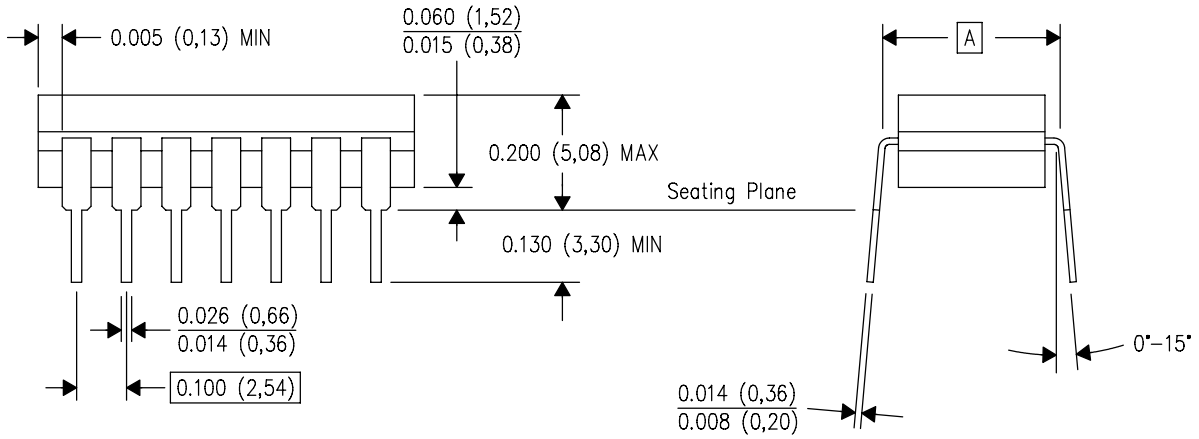
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



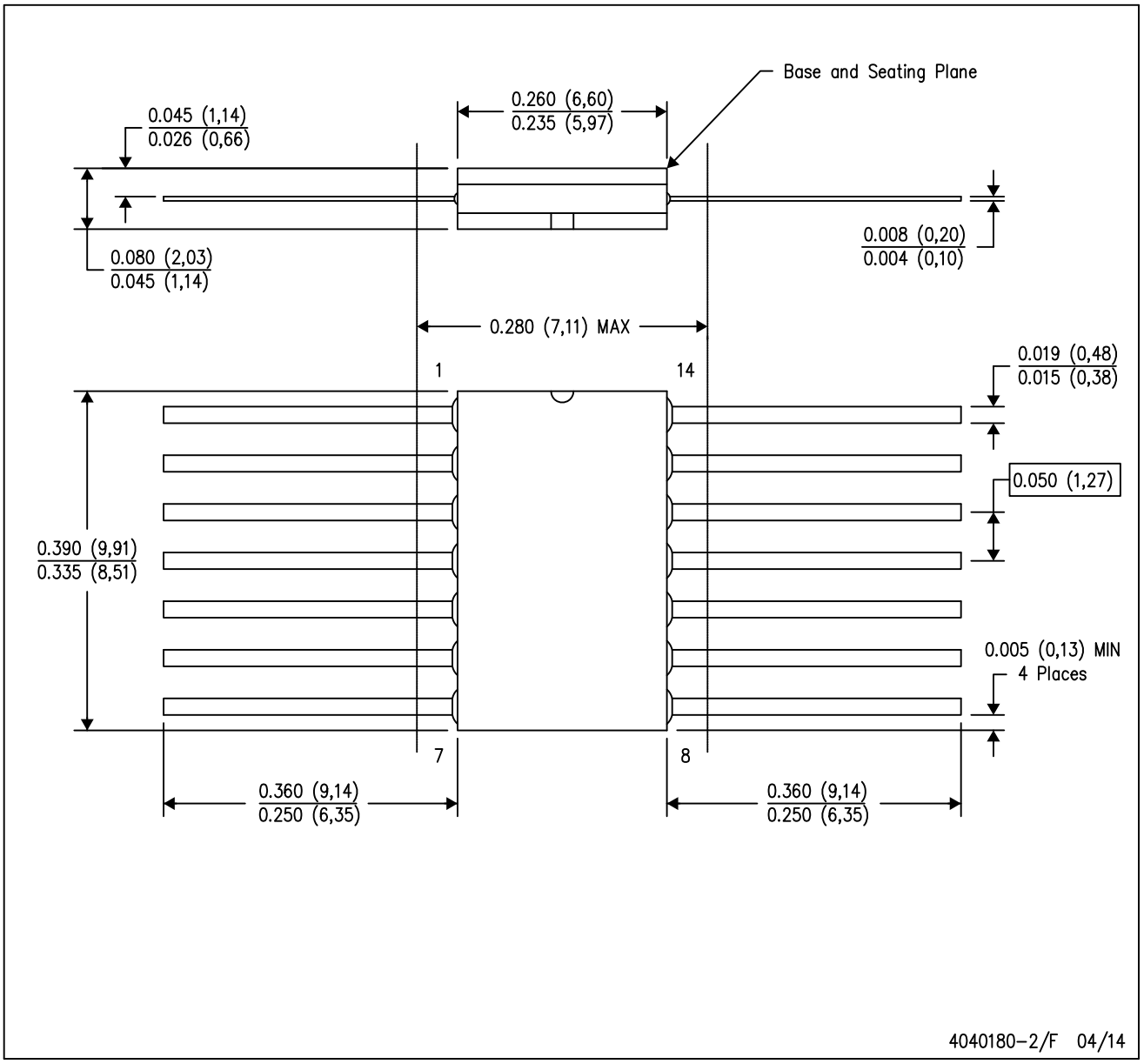
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

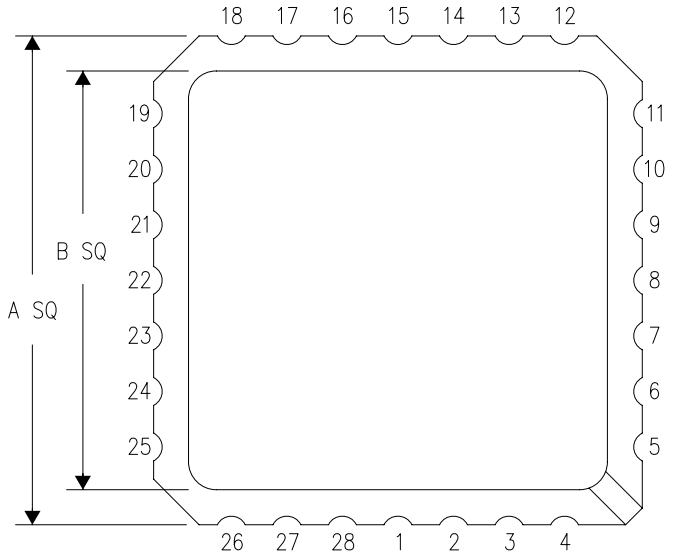
W (R–GDFP–F14) CERAMIC DUAL FLATPACK



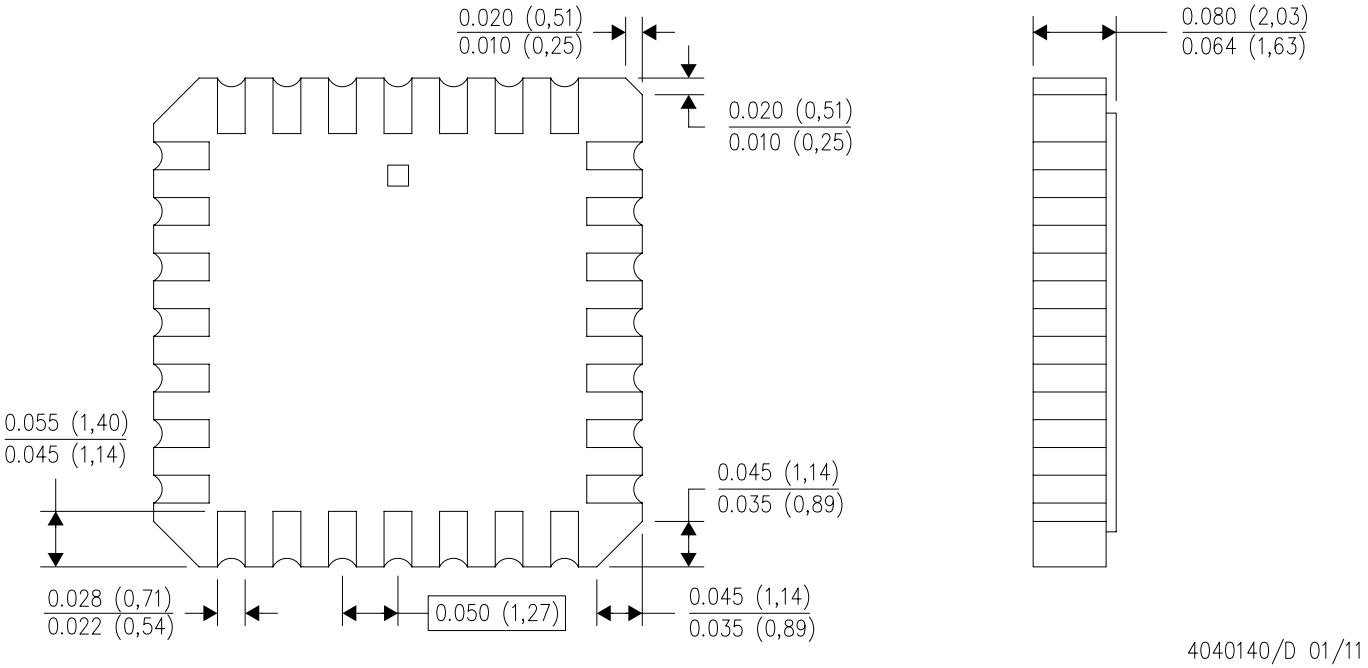
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



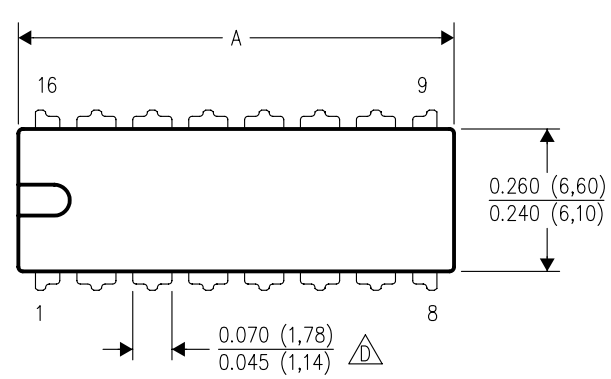
4040140/D 01/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

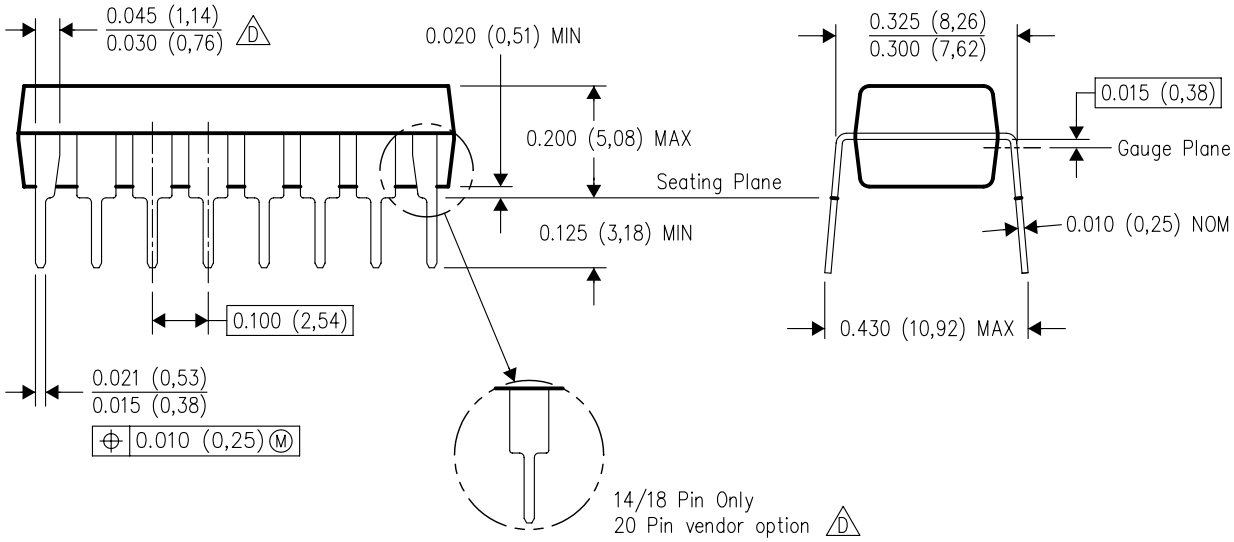
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



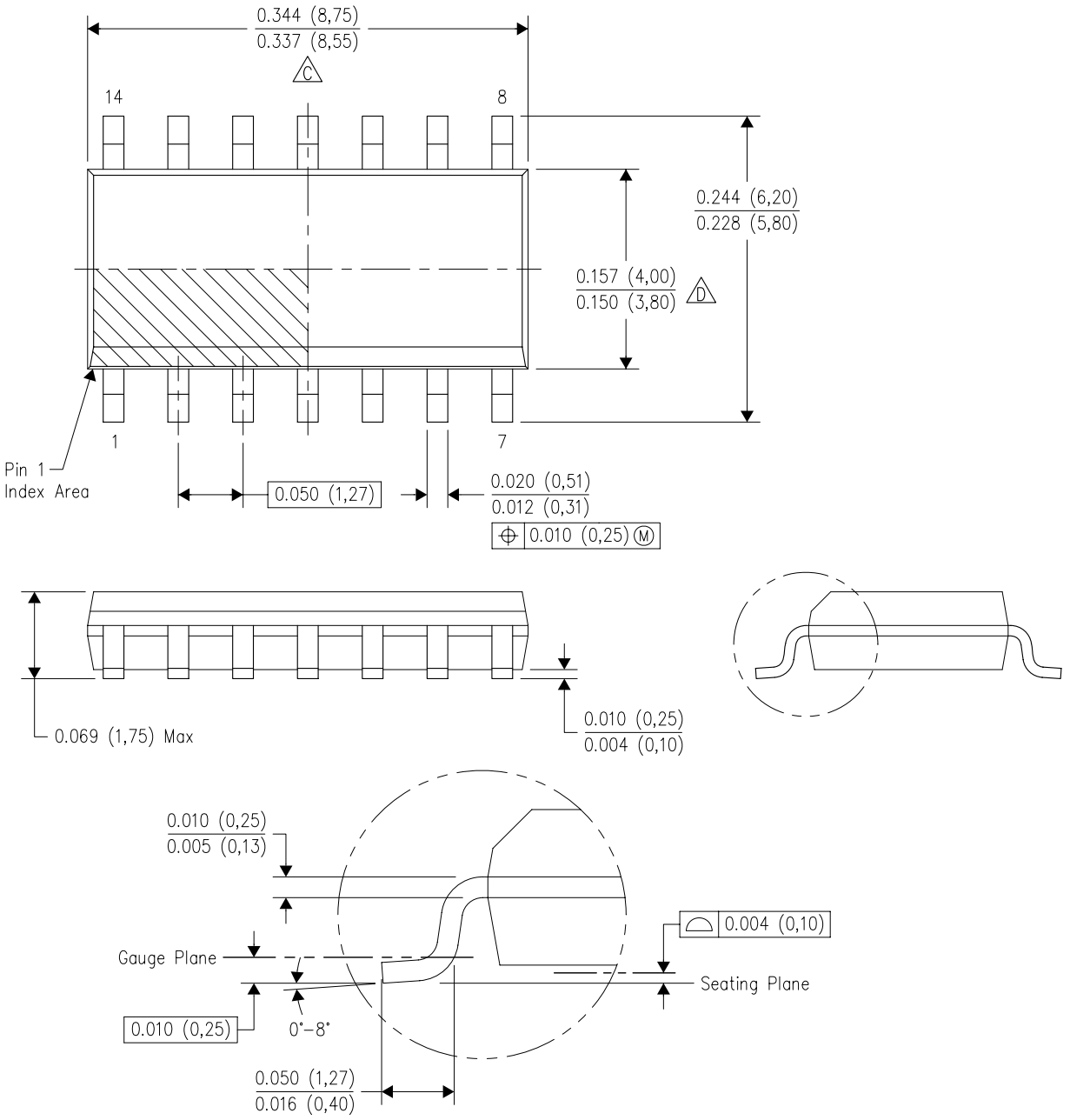
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

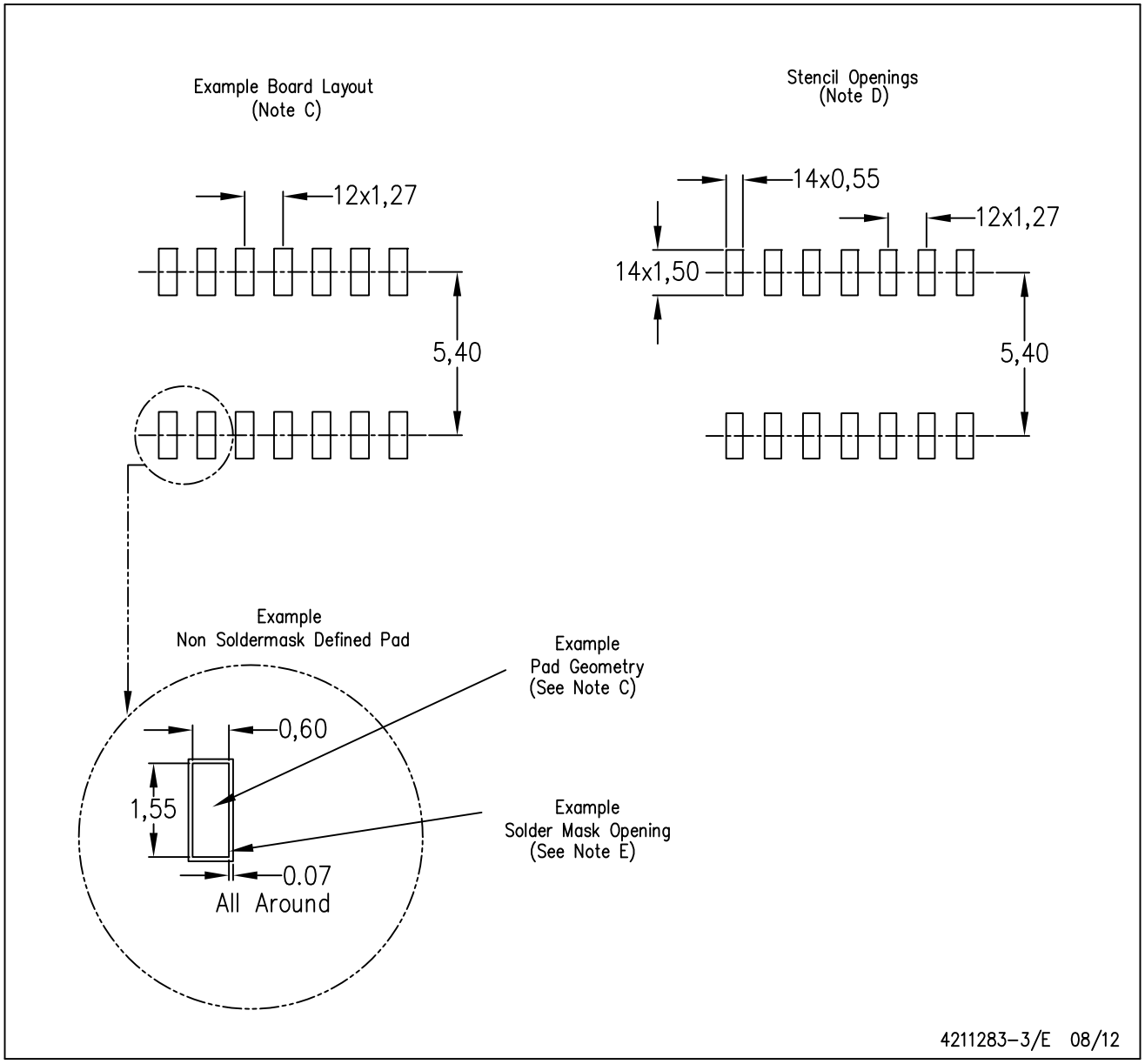
D (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040047–5/M 06/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE

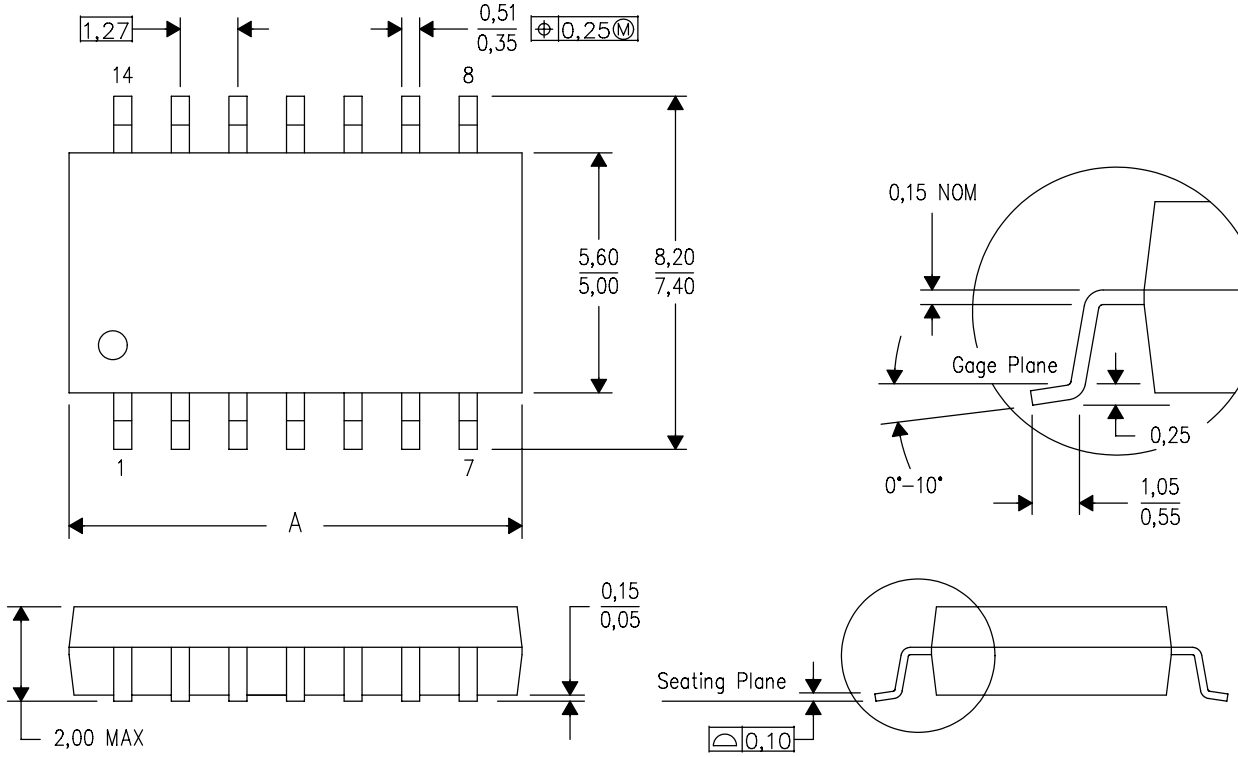


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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